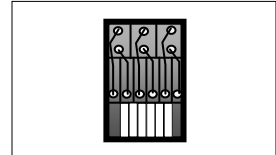


Earl J. Lum
+1-650-430-2221
elum@ejlwireless.com



**Ericsson Base Station
BFL 901 009/1 R1A
Model RBS6601 Main Unit**

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